

Internal Photographs Exhibit

Model Number: DS200

FCC ID: BWY-DS200

IC: 2483A-DS200

Applicant: McIntosh Laboratory Inc.

Date: 9/16/2025

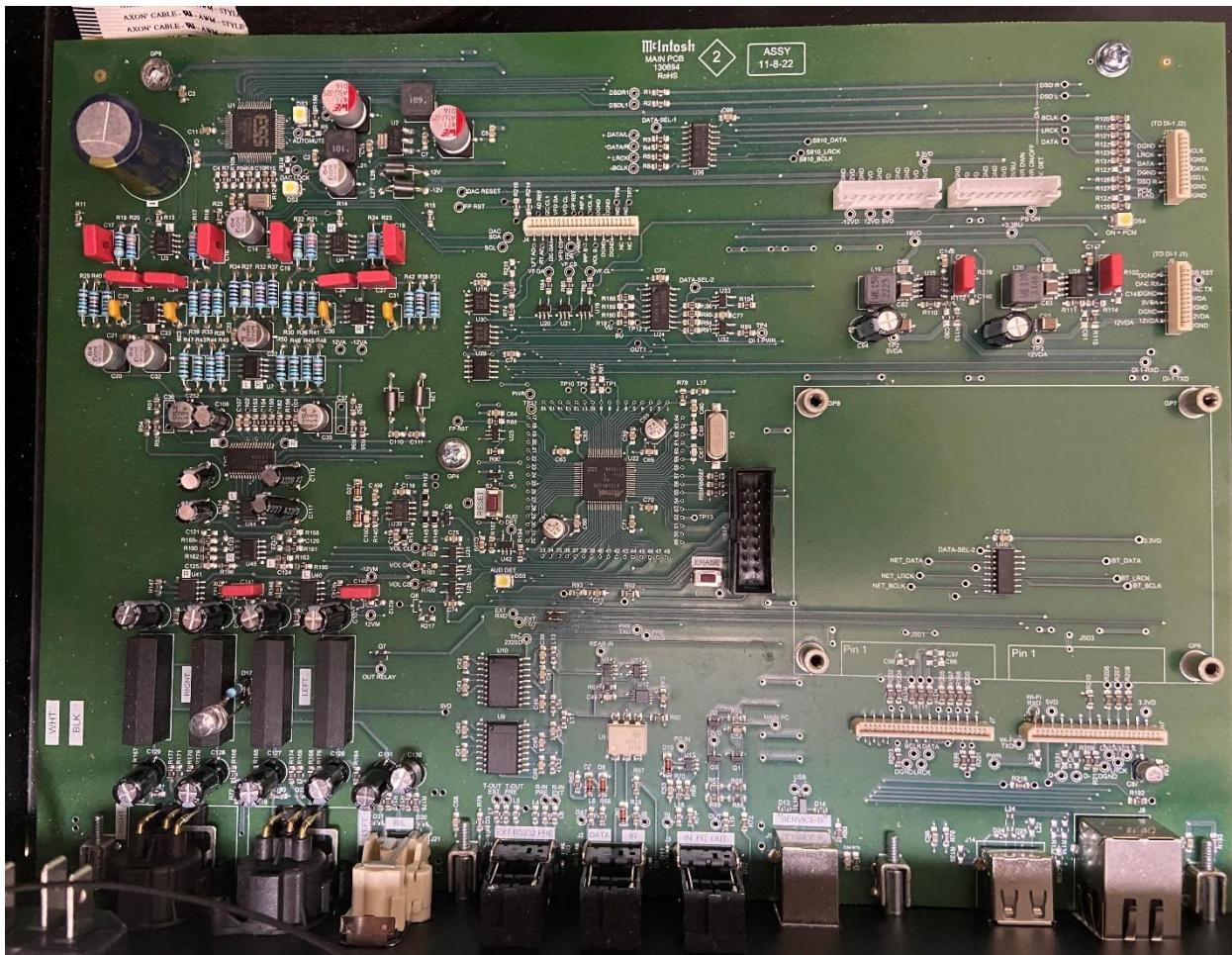
Purpose

This exhibit provides **clear and detailed internal photographs** of the subject device to show the placement and construction of all internal components related to **RF circuitry, shielding, antennas, power circuitry, and modular components**, as required under **FCC §2.1033(b)(7)** and **ISED RSS-GEN Section 3.2(e)**.

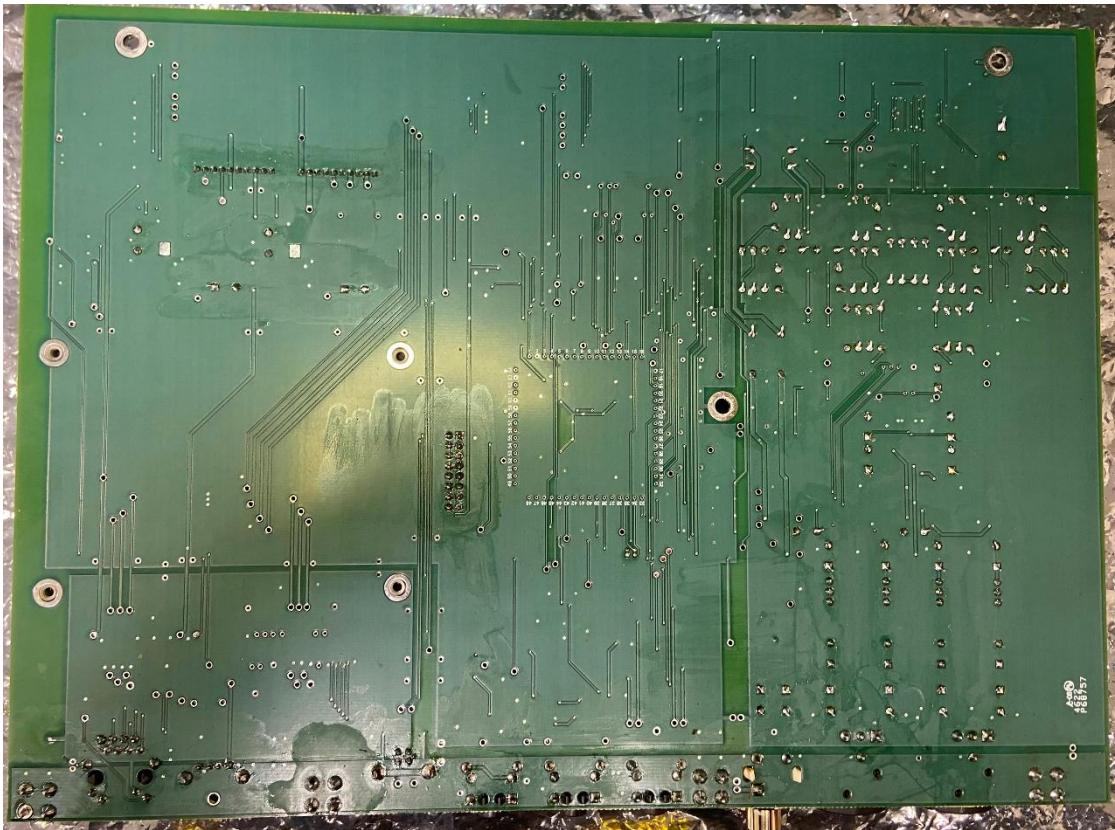
Notes (if applicable)

- All photos are representative of the production unit.
- No photos have been digitally altered except for cropping or brightness adjustments to improve visibility.

1. Overview of Main PCB (Component Side)



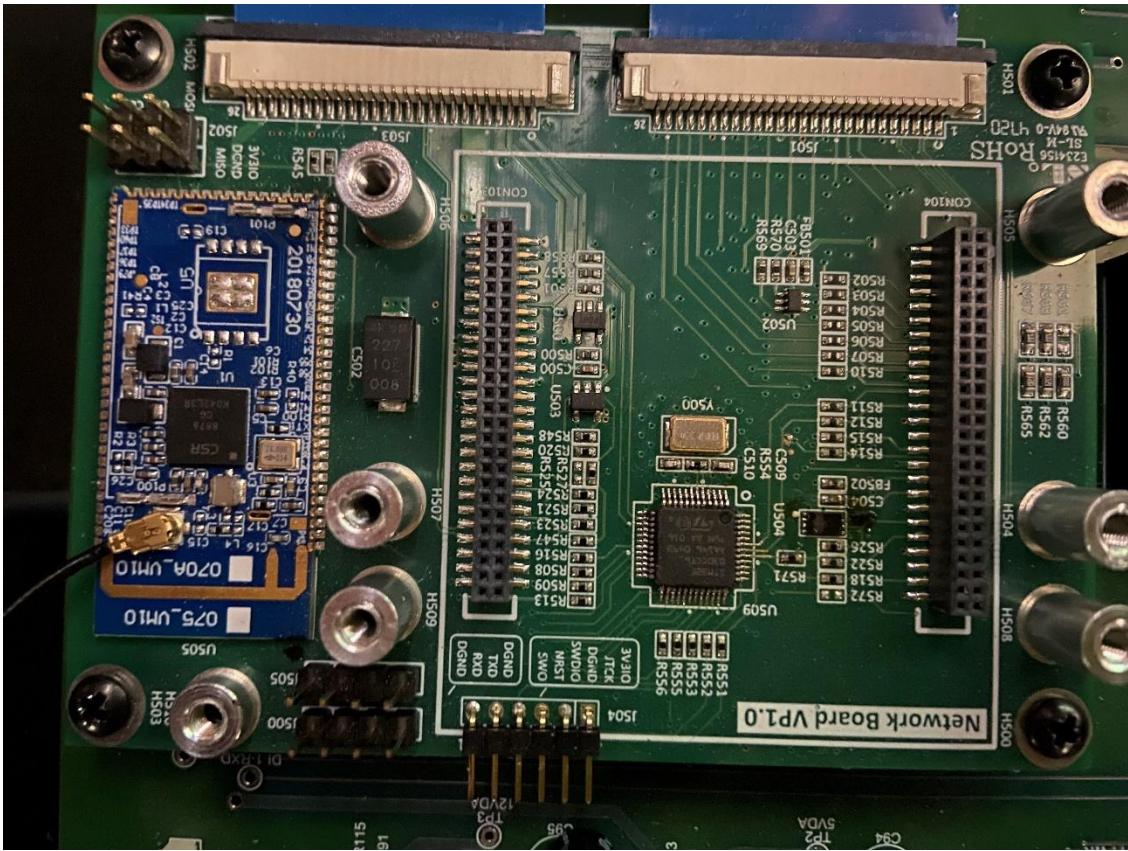
2. Overview of Main PCB (Solder Side)



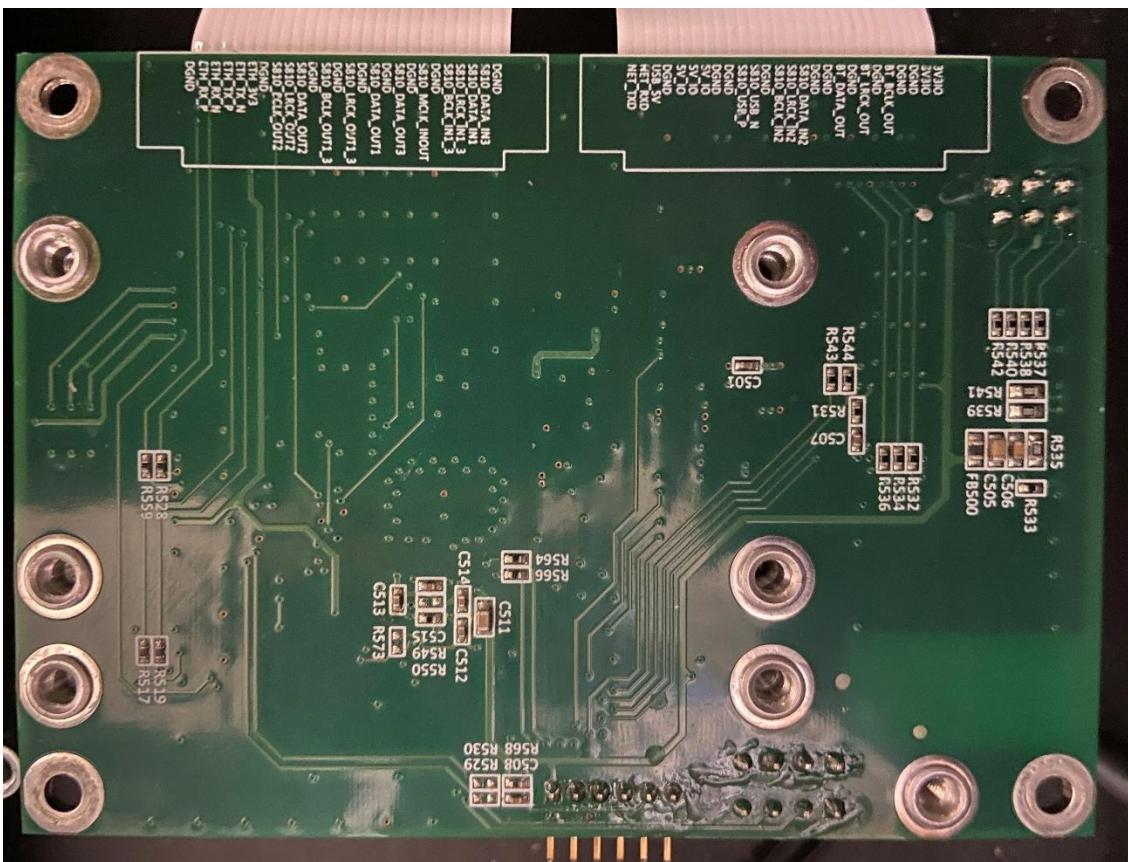
3. Antenna(s)



4. RF Module PCB top view



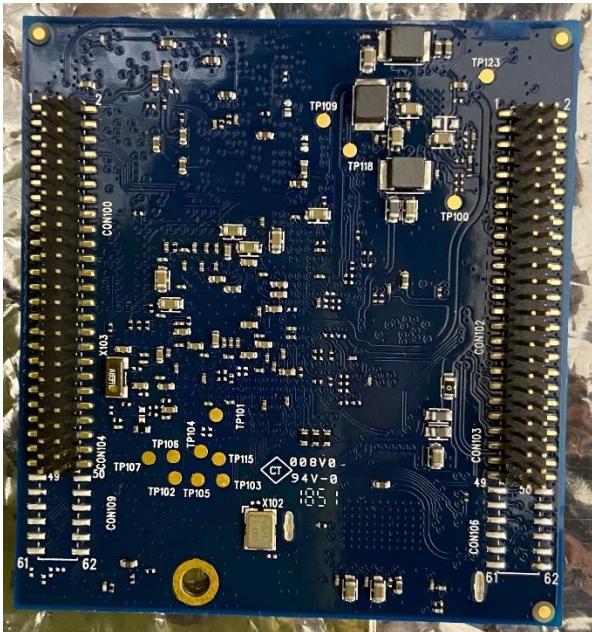
5. RF Module PCB bottom view



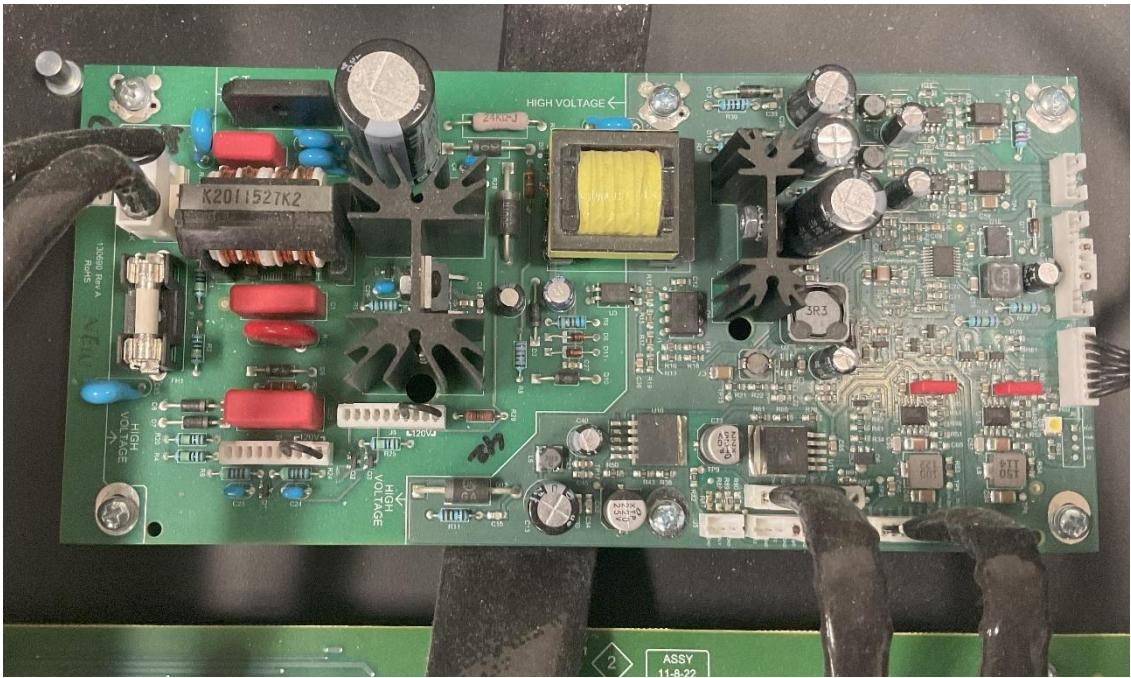
6. RF Module PCB without heatsink view



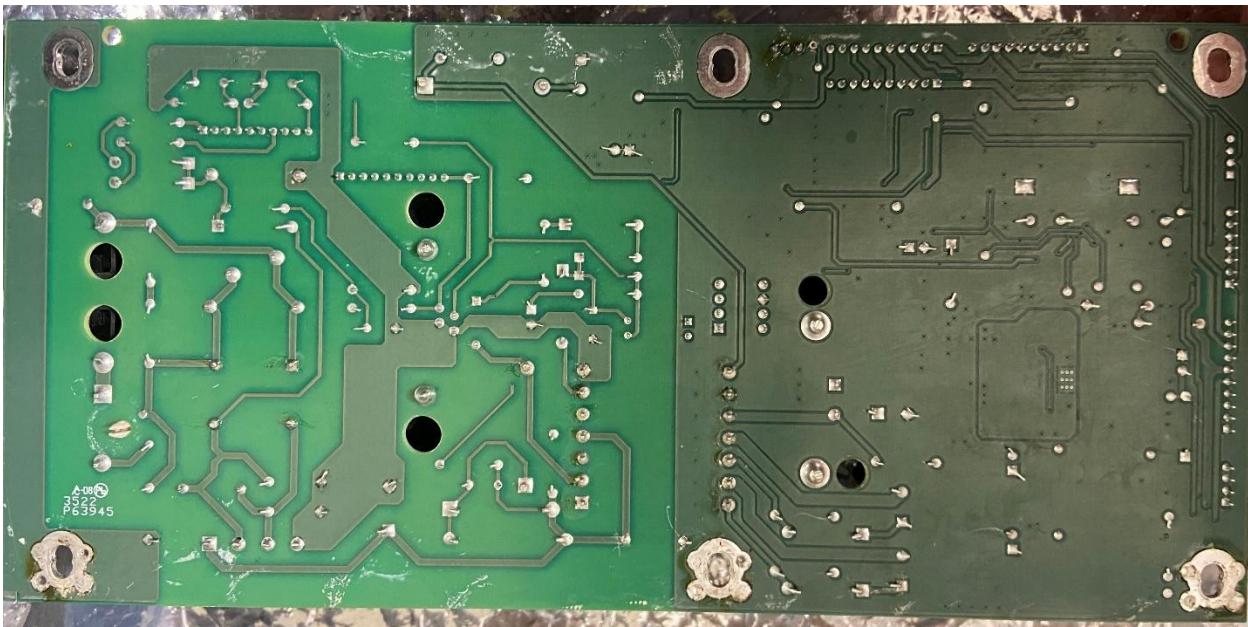
7. RF Module PCB without heatsink view bottom



8. Power Supply PCB (top view)



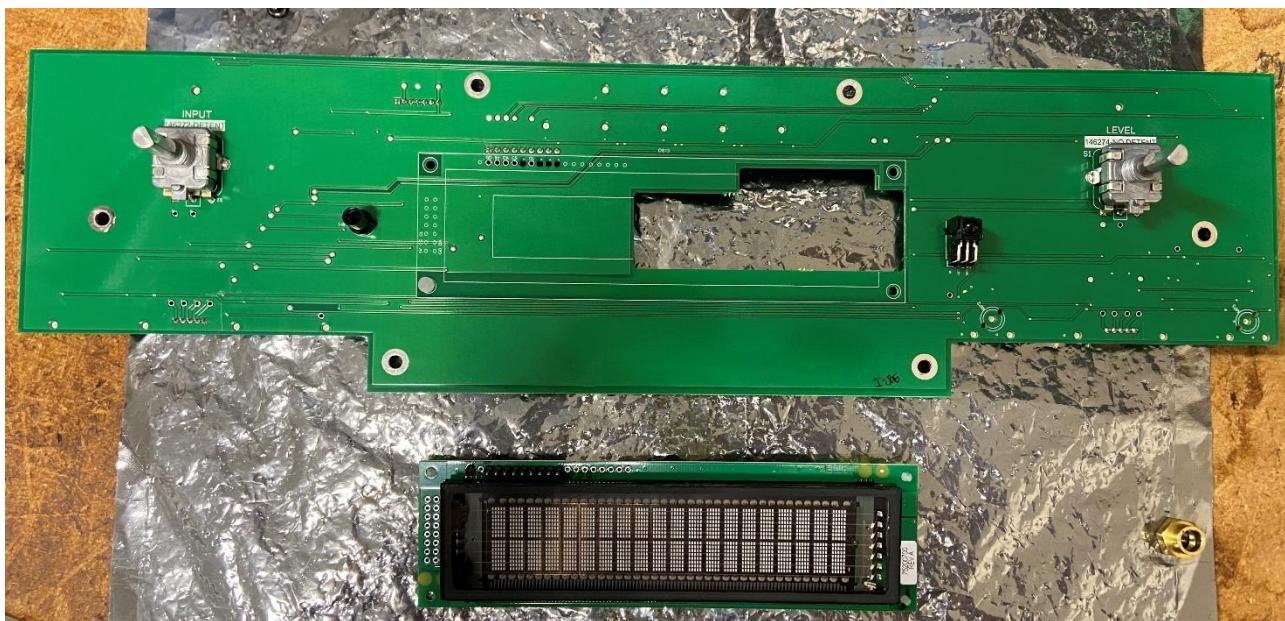
9. Power Supply PCB (bottom view)



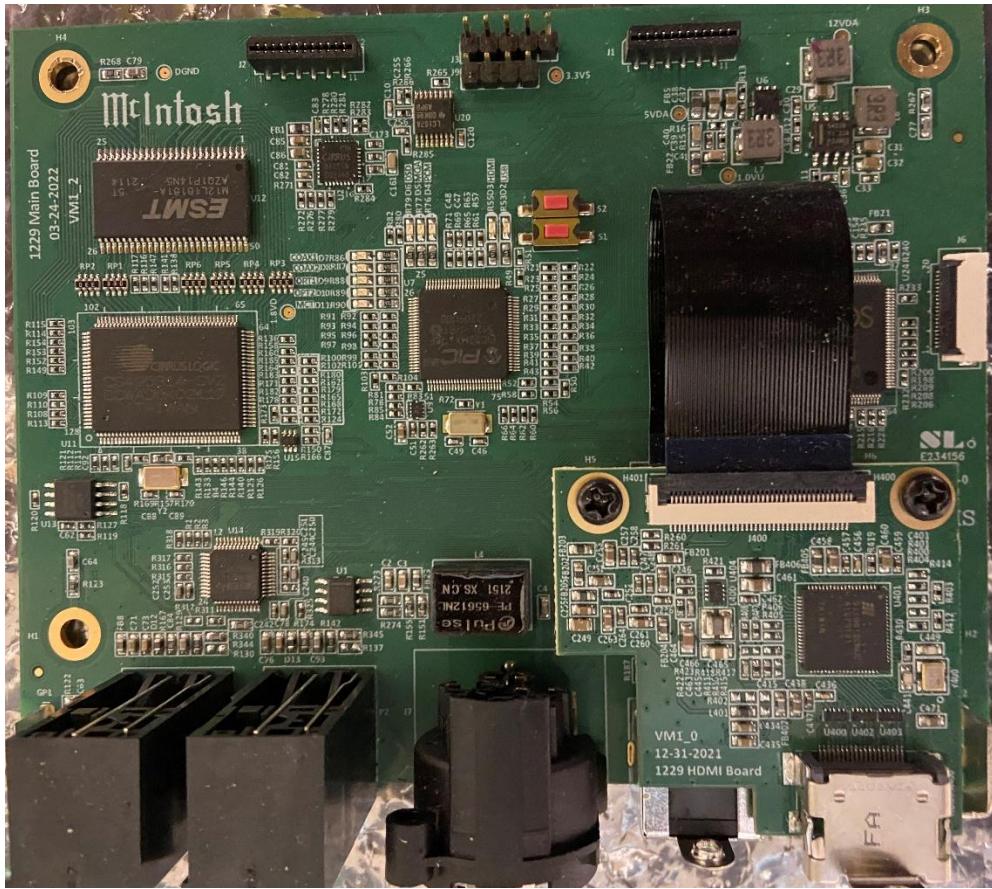
10. Interface PCB (top view)



11. Interface PCB (bottom view)



12. DAC Module top



14. Overall Device Assembly (top view)

